

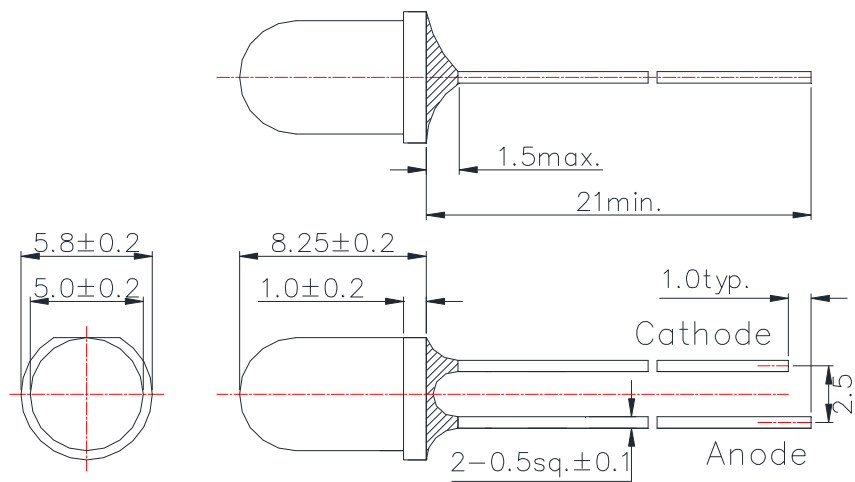
Data Sheet

L660N-03

High Bright Red LED Lamp

USHIO

Outline and Internal Circuit



(Unit : mm)

Features

- Chip Material : AlGaInP
- Chip Dimension : $350\text{um} * 350\text{um}$
- Number of Chips : 1pce
- Peak Wavelength : 660nm typ.
- Package Type : $\phi 5\text{mm}$ clear molding
- Lead Frame : Soldered (Lead Free)
- Lens : Epoxy Resin

Application

Absolute Maximum Ratings (Tc=25°C)

Item	Symbol	Rated	Unit
Power Dissipation	PD	120	mW
Forward Current	IF	50	mA
Pulse Forward Current	IFP	300	mA
Reverse Voltage	VR	5	V
Thermal Resistance	Rthja	160	K/W
Junction Temperature	Tj	120	°C
Operating Temperature	Topr	-40 ~ +100	°C
Storage Temperature	Tstg	-40 ~ +100	°C
Soldering Temperature	TSOL	265	°C

‡Pulse Forward Current condition : Duty 1% and Pulse Width=10us.

‡Soldering condition : Soldering condition must be completed with 3 seconds at 265°C.

Optical and Electrical Characteristics (Tc=25°C)

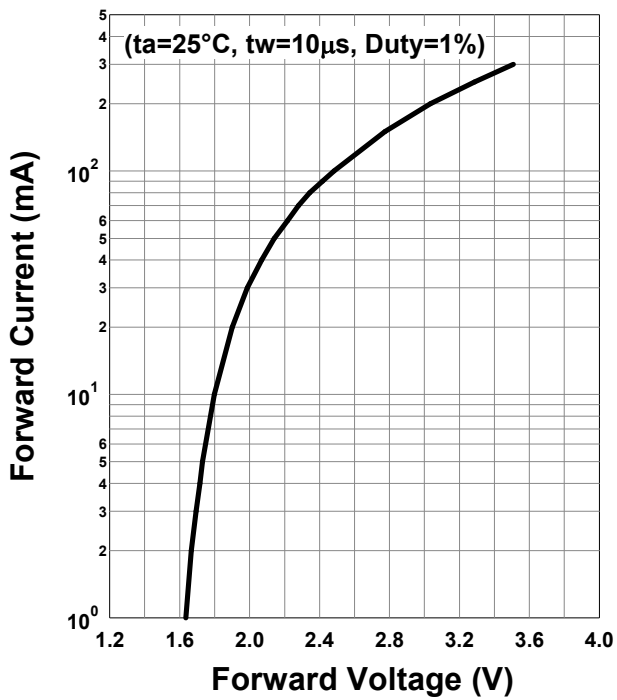
Parameter	Symbol	Min	Typ	Max	Unit	Test Condition
Forward Voltage	VF		1.9	2.3	V	IF=20mA
	VFP		3.5			IFP=300mA
Total Radiated Power	PO	8	13		mW	IF=20mA
			170			IFP=300mA
Radiant Intensity	IE		56		mW/sr	IF=20mA
			730			IFP=300mA
Luminous Flux	ΦV		870		mlm	IF=20mA
Peak Wavelength	λp	650		670	nm	IF=20mA
Dominant Wavelength	λD		640		nm	IF=20mA
Half Width	Δλ		16		nm	IF=20mA
Viewing Half Angle	θ1/2		±14		deg.	IF=20mA
Rise Time	tr		10		ns	IF=20mA
Fall Time	tf		10		ns	IF=20mA

‡ Radiated Power is measured by S3584-08.

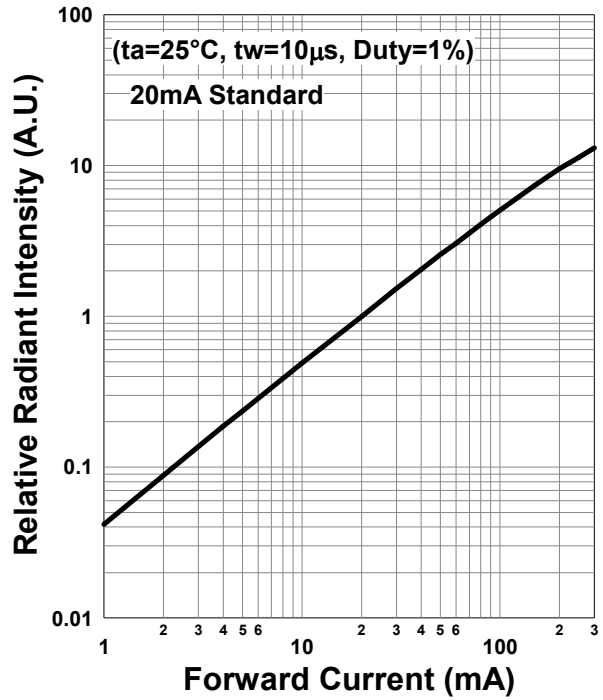
‡ Radiant Intensity is measured by CIE127-2007 Condition B.

Typical Characteristic Curves

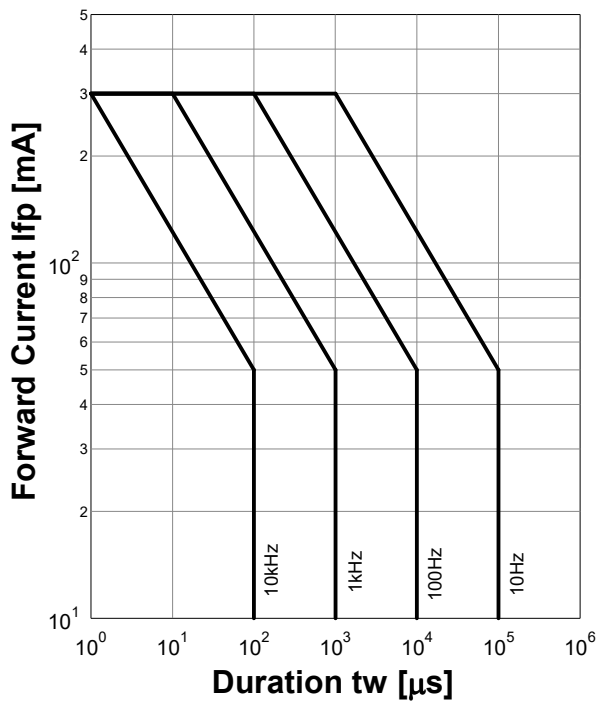
Forward Current - Forward Voltage



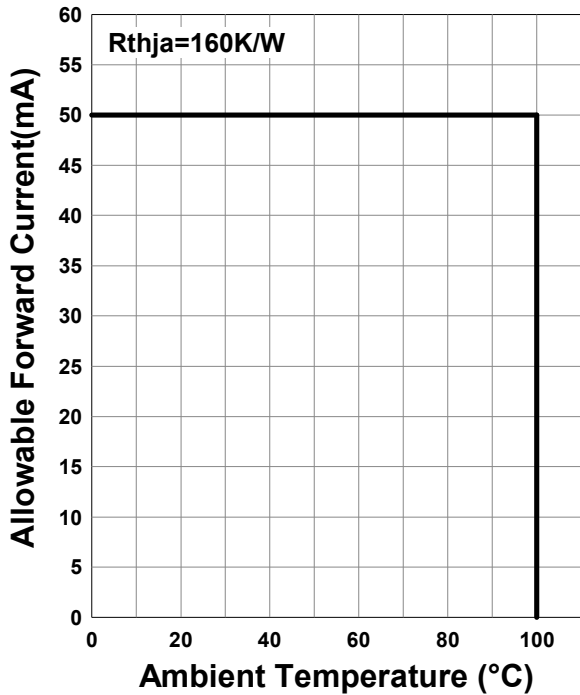
Relative Radiant Intensity - Forward Current



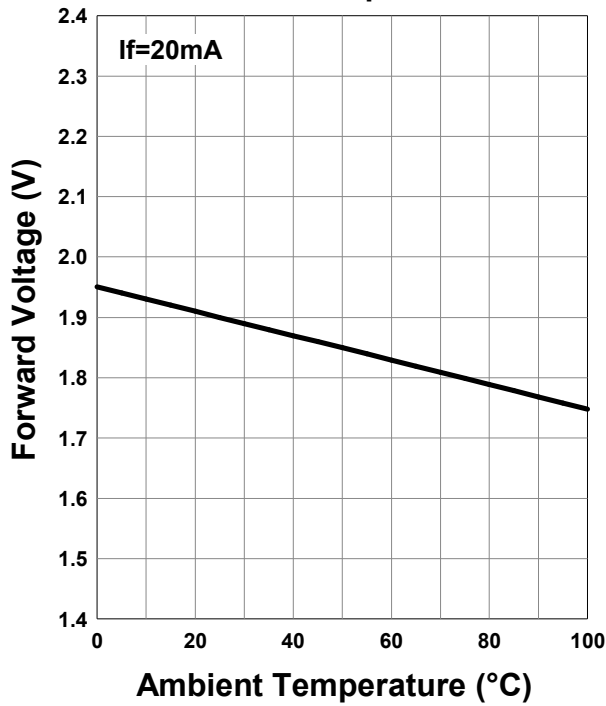
Forward Current - Pulse Duration



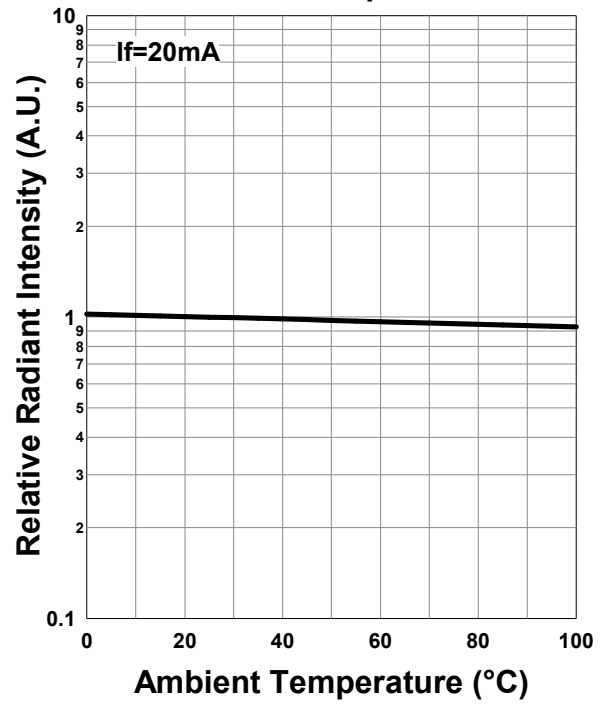
Allowable Forward Current - Ambient Temperature



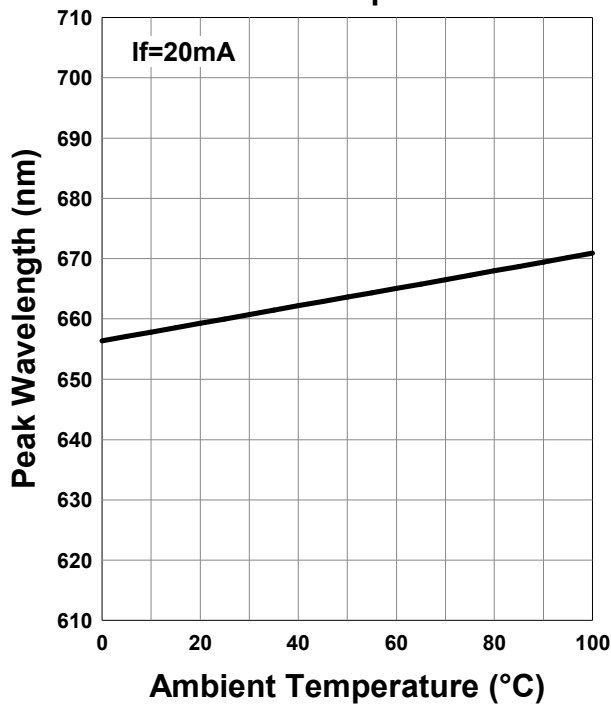
Forward Voltage - Ambient Temperature



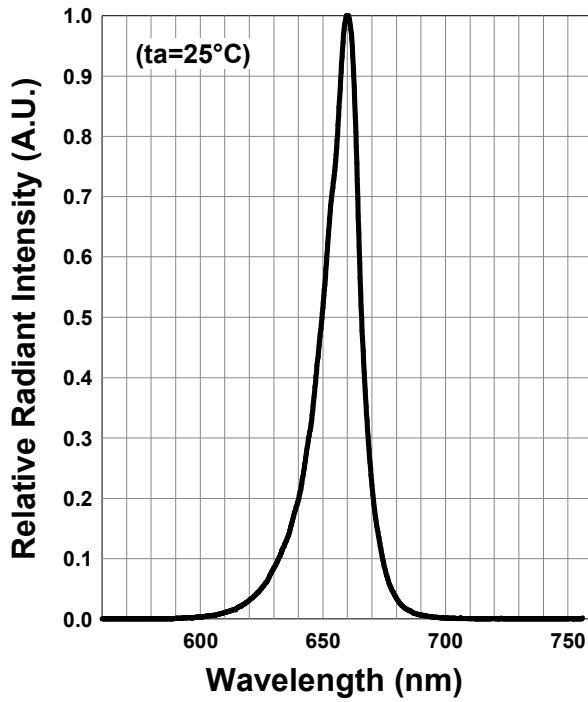
Relative Radiant Intensity - Ambient Temperature



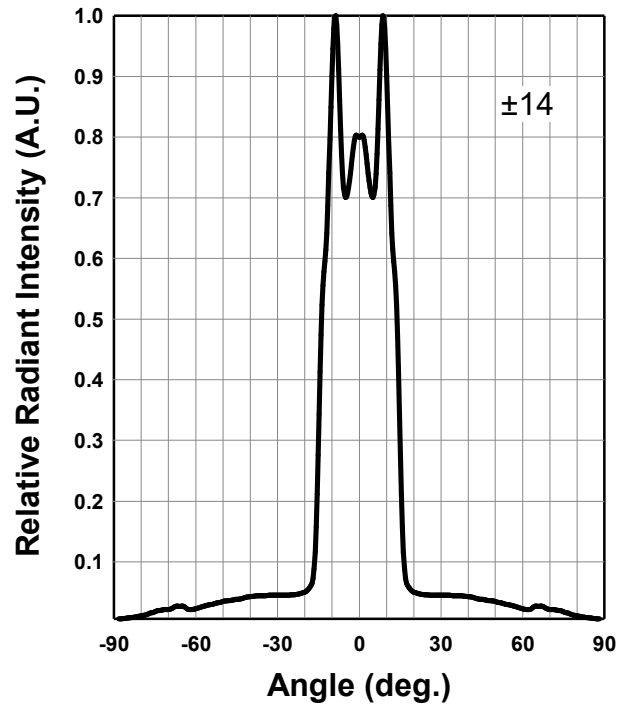
Peak Wavelength - Ambient Temperature



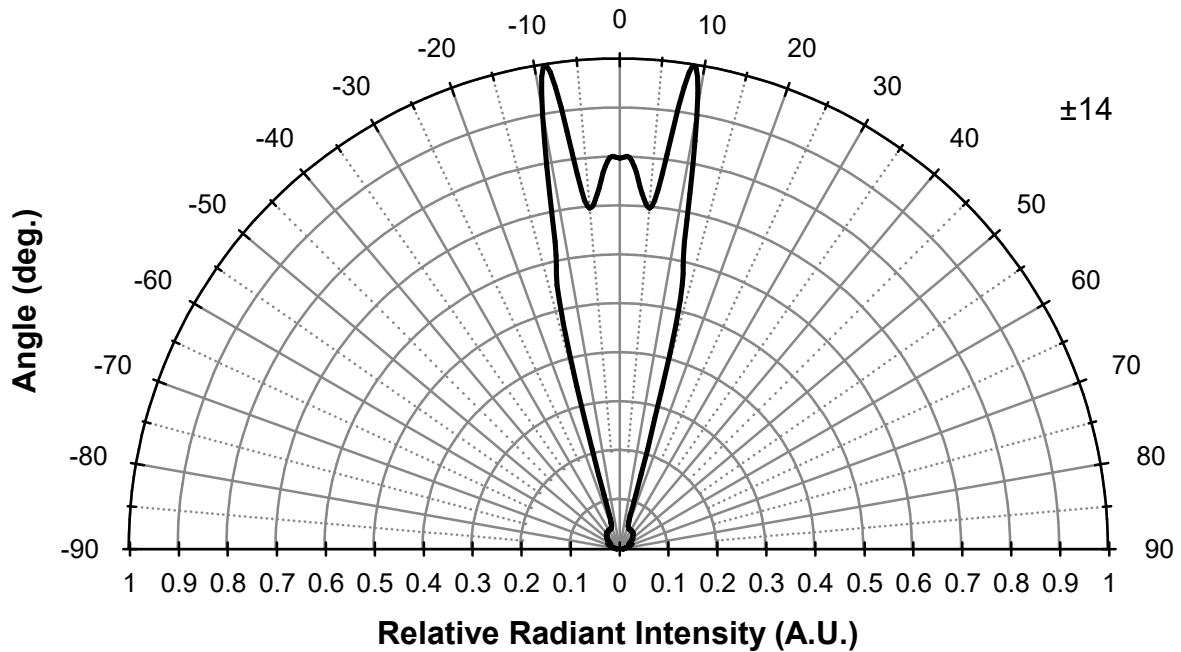
Relative Spectral Emission



Radiation Characteristics



Radiation Characteristics



Disclaimer

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Product data and parameters in this catalog are typical values based on reasonably up-to-date measurements.

Product data and parameters may vary by user application and over time.

Products shown in this catalog are intended to be used for general electronic equipment. Products are not guaranteed for applications where product malfunction or failure may cause personal injury or death, including but not limited to life-supporting / saving devices, medical devices, safety devices, airplanes, aerospace equipment, automobiles, traffic control systems, and nuclear reactor control systems.



*Effective July 2016, Ushio Epitex Inc. is now USHIO OPTO SEMICONDUCTORS, INC.